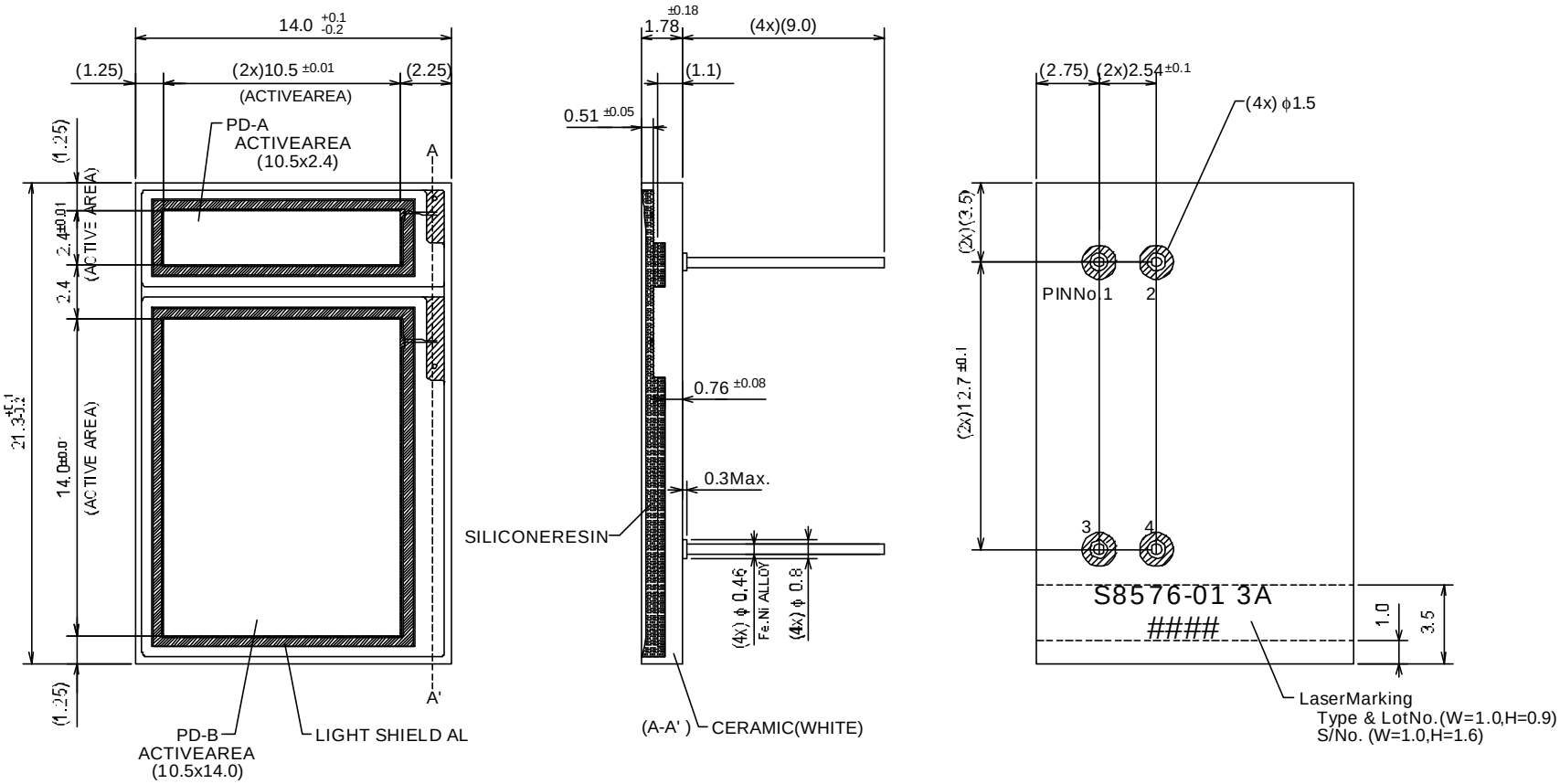

PIN CONNECTION	
1	CathodeA
2	AnodeA
3	CathodeB
4	AnodeB

Note
The silicone resin shall not extendbeyondtheuppersurfaceoftheceramicpackage.
The silicone resin shallcoverthewiresandthechips.
Leads finish : Gold andelectrolessNi
Thewholeleadssurfacegoldshallberemovedandtinnedbydippingintotwosolder(Sn96,Ag3.5)bathsheldat280deg.C.for5-10seconds.
The clearance between the diesandtheceramicwallsshallbe100µmMin.
Lead length 4mm from surface ofceramicshallbefreeofscratches.

GENERAL TOLERANCE:±0.2

GLAST LAT CAL Dual PIN Photodiode
LAT-DS-01237-03

MARK	CONTENTS	DATE	APPR	CHCK	CHCK	DESN	DRAW
c							
b							
a							
	FIRSTISSUE ...	2003.02.25					

UNIT mm | SCALE 5/1 | TITLE S8576-01
PROJ | DWG.No KQC-B14514 | REV A
REF

HAMAMATSU PHOTONICS K.K.
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